



Features

- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

RELFUSE

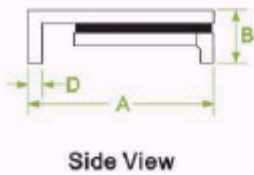


LP-SM series

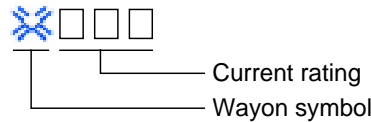
Surface-mount devices

Product Dimensions(mm)

Part number	A	B	C	D
	Max.	Max.	Max.	Max.
LP-SM030	7.98	3.18	5.44	0.70
LP-SM050	7.98	3.18	5.44	0.70
LP-SM075	7.98	3.18	5.44	0.70
LP-SM110	7.98	3.00	5.44	0.70
LP-SM125	9.50	3.00	5.00	0.70
LP-SM130	9.50	3.00	6.71	0.70
LP-SM150	9.50	3.00	6.71	0.70
LP-SM185	9.50	3.00	6.71	0.70
LP-SM200	9.50	3.00	6.71	0.70
LP-SM250	7.98	3.18	6.71	0.70
LP-SM260	7.98	3.18	5.44	0.70
LP-SM300	7.98	3.18	5.44	0.70



Marking System



Electrical Characteristics

Part number	I_H	I_T	V_{max}	I_{max}	T_{trip}		Pd_{typ}	R_{min}	R_{1max}
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	()	()
LP-SM030	0.30	0.60	60	10	1.5	4.0	1.9	0.700	4.80
LP-SM050	0.50	1.00	60	10	2.5	4.0	1.9	0.350	1.400
LP-SM075	0.75	1.50	60	40	8.0	3.0	1.9	0.290	1.000
LP-SM110	1.10	2.20	33	40	8.0	0.20	1.9	0.100	0.480
LP-SM125	1.25	2.50	24	40	8.0	0.20	1.6	0.070	0.250
LP-SM130	1.30	2.60	33	40	8.0	4.0	2.1	0.080	0.280
LP-SM150	1.50	3.00	33	40	8.0	5.0	2.1	0.060	0.250
LP-SM185	2.00	3.70	15	40	8.0	5.0	2.1	0.045	0.165
LP-SM200	2.50	4.00	15	40	8.0	12.0	2.1	0.045	0.125
LP-SM250	2.60	5.00	15	40	8.0	25.0	1.9	0.025	0.085
LP-SM260	3.00	5.20	6	40	8.0	20.0	1.9	0.025	0.075
LP-SM300	2.60	6.00	6	40	8.0	35.0	1.9	0.015	0.048

I_H =Hold current: maximum current at which the device will not trip at 25 °C still air.

I_T =Trip current: minimum current at which the device will always trip at 25 °C still air.

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

T_{trip} =Maximum time to trip at assigned current.

Pd_{typ} =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

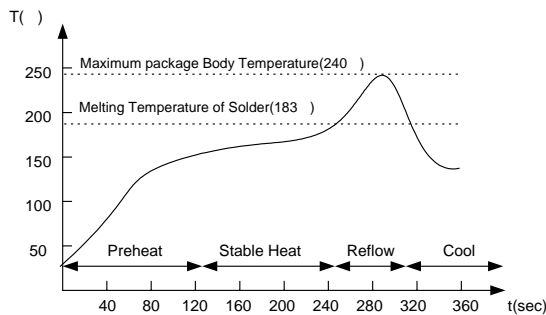
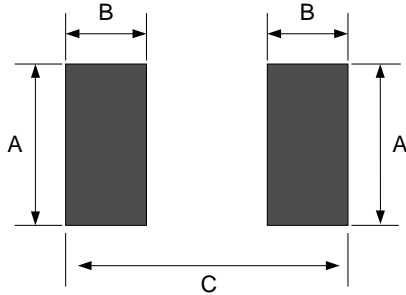
R_{min} =Minimum device resistance at 25 °C prior to tripping.

R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	R_{min} R R_{1max}
Time to Trip	Specified current, V_{max} , 25	T maximum Time to Trip
Hold Current	30min, at I_H	No trip
Trip Cycle Life	V_{max} , I_{max} , 100cycles	No arcing or burning
Trip Endurance	V_{max} , 24hours	No arcing or burning

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-SM030	3.1	2.3	9.7
LP-SM050	3.1	2.3	9.7
LP-SM075	3.1	2.3	9.7
LP-SM110	3.1	2.3	9.7
LP-SM125	3.1	2.3	9.7
LP-SM130	4.6	2.3	10.7
LP-SM150	4.6	2.3	10.7
LP-SM185	4.6	2.3	10.7
LP-SM200	4.6	2.3	10.7
LP-SM250	4.6	2.3	10.7
LP-SM260	3.1	2.3	9.7
LP-SM300	3.1	2.3	9.7

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel:

LP-SM030~ LP-SM125.....2000pcs per reel
 LP-SM260~ LP-SM300.....2000pcs per reel
 LP-SM130~ LP-SM250.....1500pcs per reel